

Gudeng Precision Industrial Co. Ltd

家登精密工業股份有限公司



2023.3

Partner with **H.E.A.R.T.** , Grow with **P.A.S.S.I.ON.**

COO Amy Shen
(02)2268-9141
AmyShen@gudeng.com

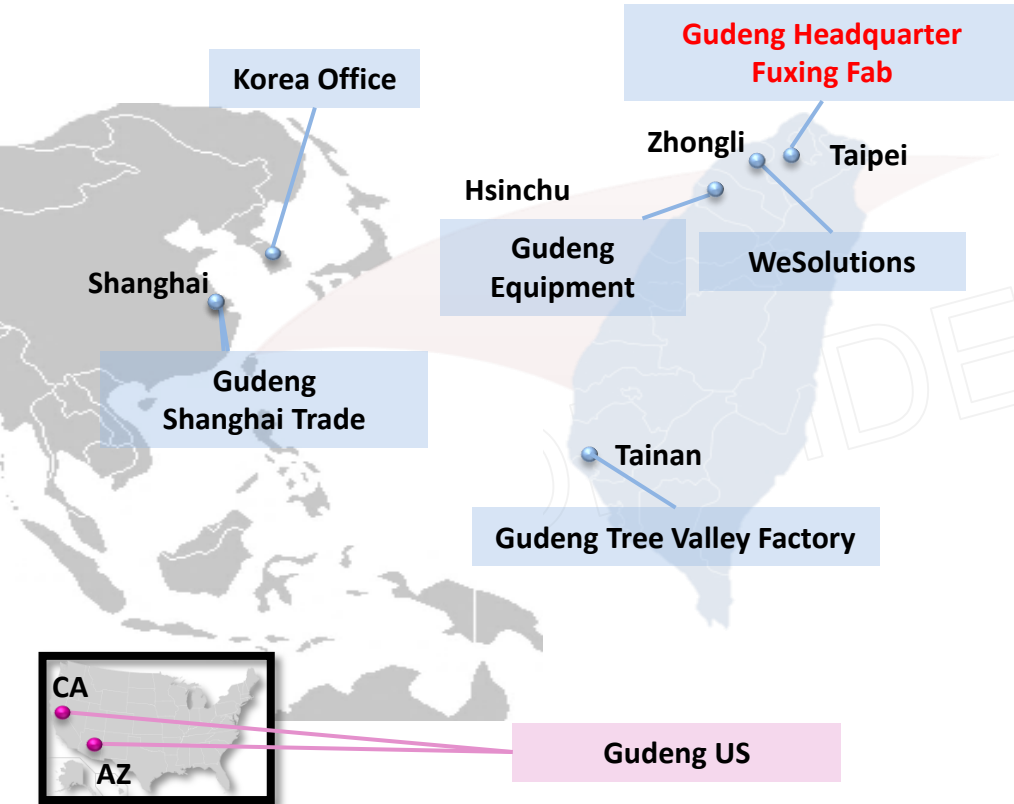
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This presentation includes forward-looking statements. Forward-looking statements refer to statement that address activities, events or developments that Gudeng Precision expects or anticipates will or may occur in the future (including but not limited to projections, targets, estimates, market share, total addressable market (TAM) and business plans).

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Gudeng Company Overview



- ▶ Established : Mar. 20th , 1998
 - ▶ Employee : **815**
 - ▶ Capital : US\$ **28** million
 - ▶ **2020** Group Revenue : US\$ **83** million
 - ▶ **2021** Group Revenue : US\$ **104** million
 - ▶ **2022** Group Revenue : US\$ **150** million
- (no auto business revenue since Q2)

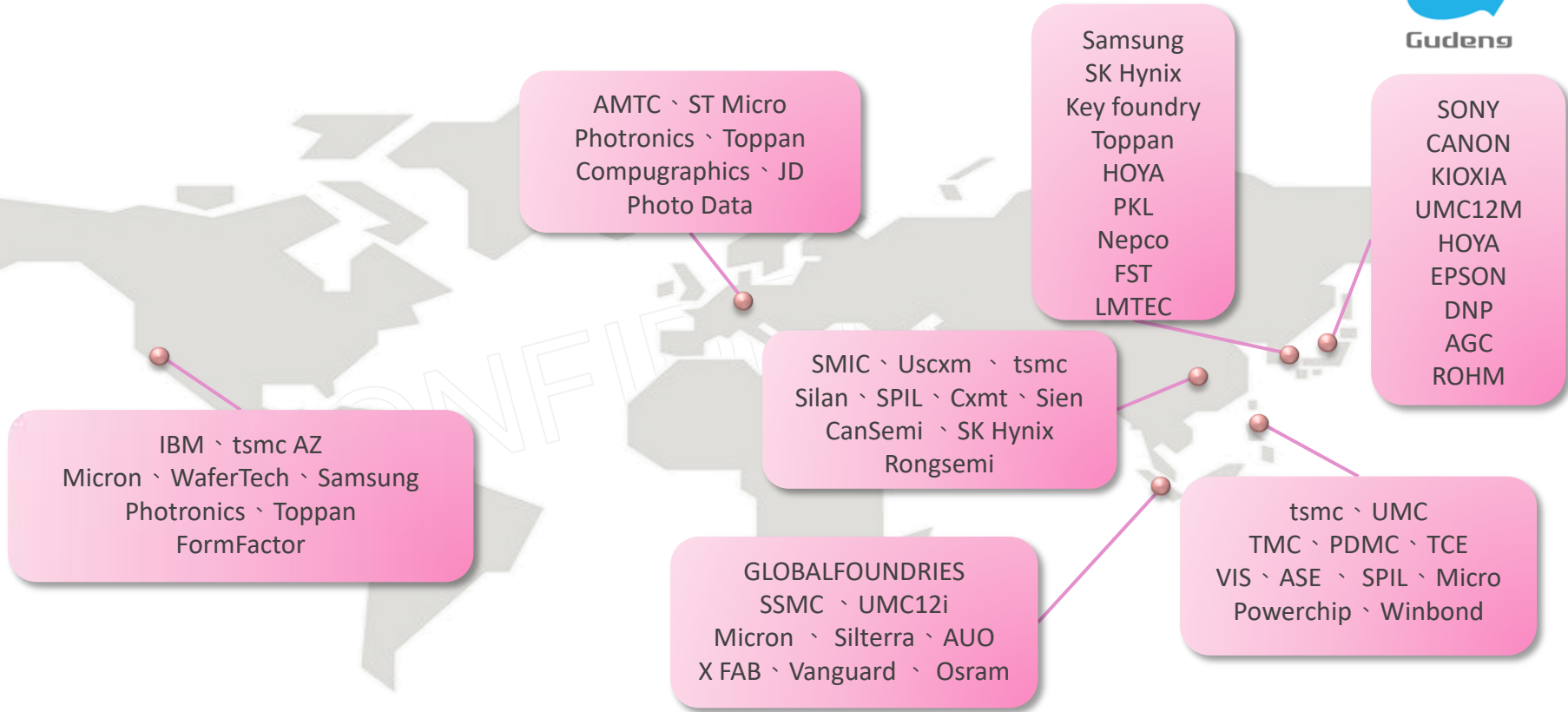
▶ Main Product :

Semiconductor

- Mask Handling Solutions
- Wafer Handling Solutions
- Equipment
- Other Service

Aerospace

Customers



Gudeng Total Solutions



Product Line

Mask Carriers



Wafer Carriers



Logistic Automation Solutions



	Product Design	Front End	OSAT/ Back end
	IC Design / Mask maker	Foundry/ IDM	Assembly/ Wafer sorting/ Final Test
Mask Carriers	V	V	V
Wafer Carriers		V	V
Automation	V	V	

Gudeng Total Solutions

Semiconductor Mature to Advanced Process

Gudeng Key Wafer Carriers

Process : 12" FOUP

Shipping : FOSB

Packaging : FP FOUP



Semiconductor Production Process

Product Design

Front End

Back End

Board Assembly

IC Design

Mask Maker

Foundry

Wafer Sort

Assembly

Final Test

Board Assembly

Board Testing

- Communication
- Automotive
- Consumer Electronics
- National Defense
- PC/NB

- Circuit Design
- Engineering Test

- Materials Fab
- Wafer Bank

- Wafer Bumping
- Wafer Probing

- Module, Board Assembly & Test



3D Advanced Packaging FP FOUP



- To continue the validity of Moore's Law, 3D advanced packaging technology has begun to enter a rapid growth
- 2021 3D packaging global capex will reach 11.9 billion US dollars, with a high growth rate in the next three years
- Gudeng is the first to develop 3D advanced packaging FP FOUP, with market leadership and pricing power



- ❑ High-efficiency protection for 510x510 PCB during transportation and storage
- ❑ Maintain a clean environment with low humidity inside the FOUP, effectively reducing the risk of PCB contamination
- ❑ Compatible with AGV transportation

Market

Taiwan: tsmc 、 Unimicron 、 NanYa PCB 、 KINSUS
Overseas: INTEL 、 Ibsiden 、 Samsung 、 AT&S

Gudeng Revenue

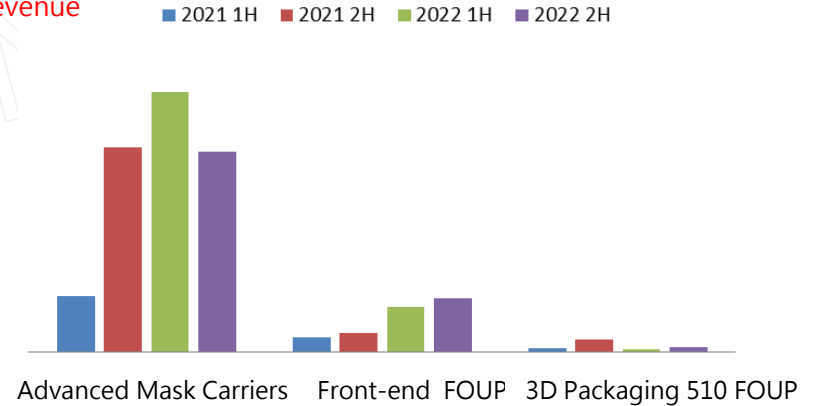


2022 Jan.~Dec. Key Product Revenue Performance :

Advanced Mask Carriers US\$ **52** million **50% of the carrier revenue**
 RSP Carriers US\$ **19** million **18% of the carrier revenue**
 FOUP US\$ **19** million **18% of the carrier revenue**

	2021 1H	2021 2H	2022 1H	2022 2H
Product	Revenue			
Advanced Mask Carriers	6,344,557	23,425,144	29,680,599	22,908,274
Front-end FOUP	1,643,997	2,092,293	5,084,396	6,172,400
3D Packaging PCB FOUP	392,933	1,394,900	226,100	470,204
Total	8,381,487	26,912,337	34,991,095	29,550,878

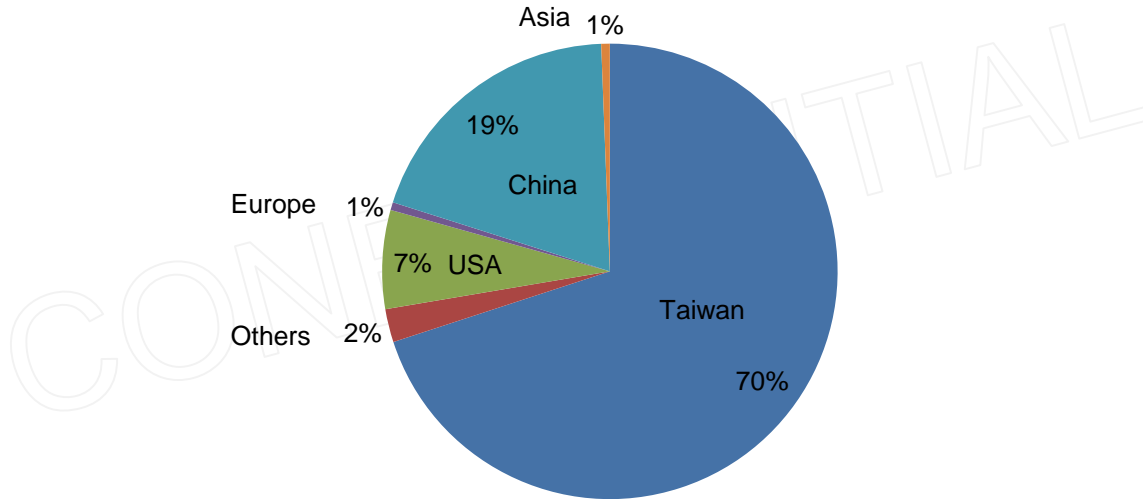
US dollars



Gudeng Regional Revenue



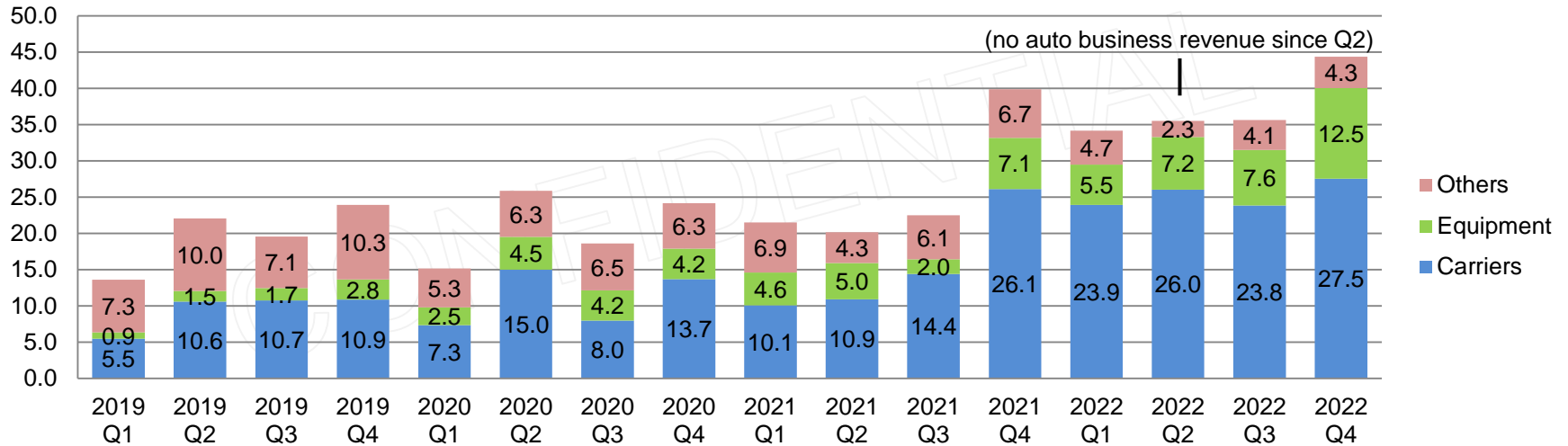
2022 Gudeng Revenue



Gudeng Revenue by quarter



Consolidated Revenue



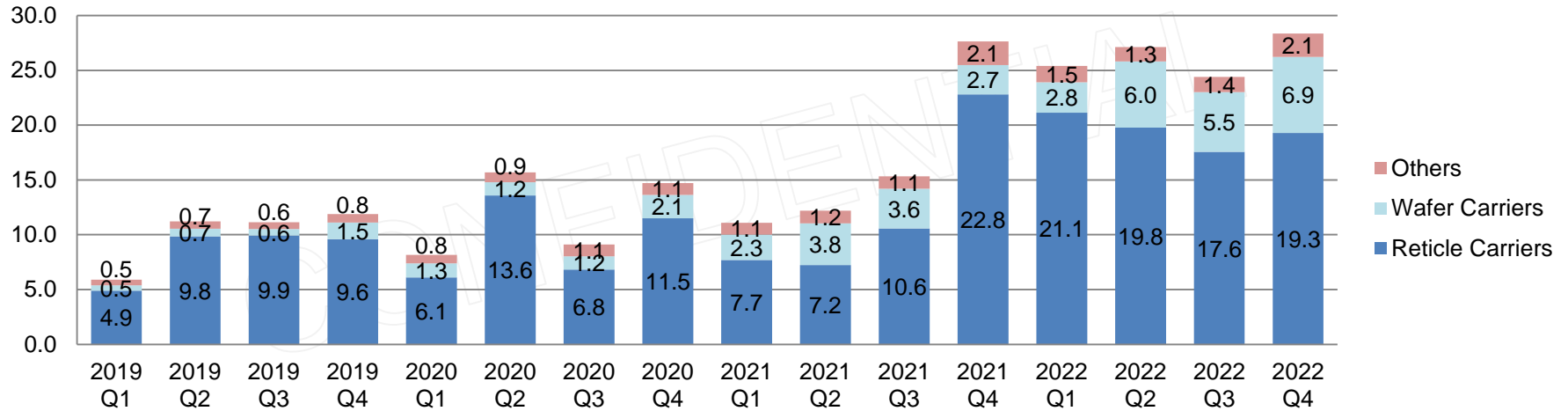
US million dollars

2022 Jan. US \$11 million revenue including auto business about 1.3 million
 2023 Jan. US \$10.4 million revenue with no auto business

Gudeng Revenue by quarter



Core Business Revenue



US million dollars

Gudeng Strategies Overview



- Gudeng business covers the world and remains strong growth power
- China Market :
 - ◆ Reticle and wafer carriers 'market share continue to grow and take the place of other suppliers
 - ◆ Capacity is sufficient to support the entire China market
 - ◆ Accelerate the production base plan in China
- US Market :
 - ◆ Focus on advanced processes and aim to become main source of key customers
 - ◆ EUV, 3D packaging(Panel FOUP) shipments are steadily increasing
- Taiwan Market :
 - ◆ Following Taiwan major customer global plan, Gudeng has become its main global supplier
 - ◆ Wafer carriers certification completed by key customer, driving global customers to follow up
- Gudeng subsidiary – Gudeng Equipment, will grow simultaneously with carriers
- Aerospace materials have completed verification and started shipping, with significant revenue in 2023 and high speed growth in 2024



Thank You
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